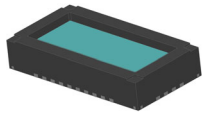
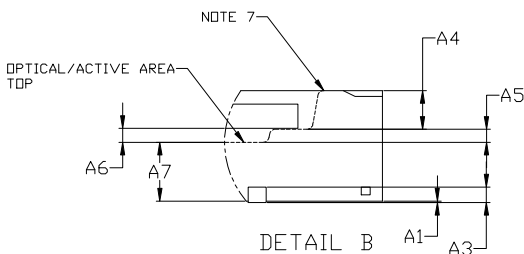
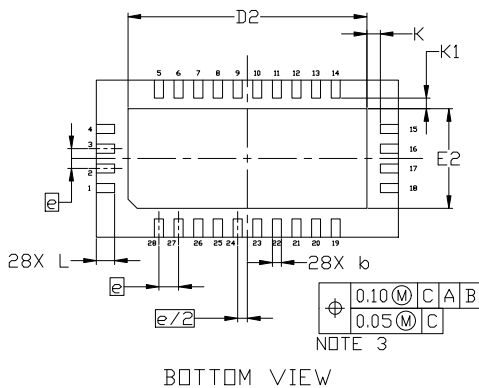
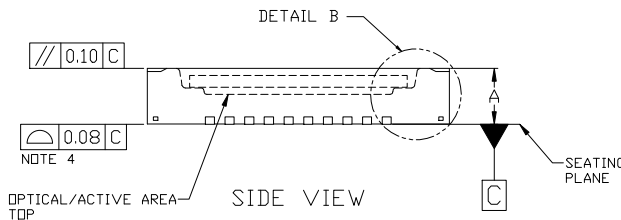
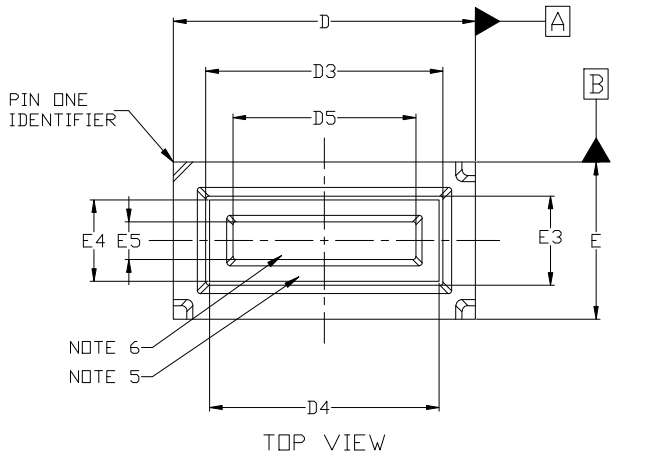


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**QFN28 10.00x5.20x1.85, 0.65P**  
CASE 485FZ  
ISSUE F

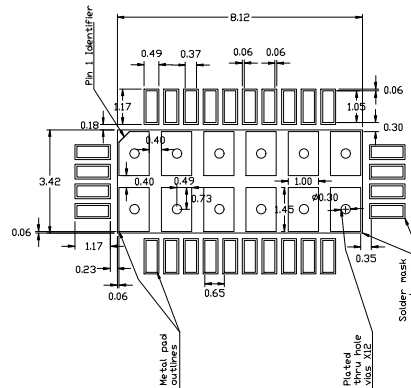
DATE 14 JUL 2023



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. GLASS LID AREA, 0.4mm THICKNESS. DEFINED BY D4 & E4.
6. OPTICAL/ACTIVE AREA IS CENTERED.  
ALIGNMENT TO PACKAGE CENTER: +/- 0.05 mm  
ROTATION ALLOWED: +/- 0.5°
7. MOLD INNER CAVITY RADIUS AT 0.1mm AT 10° DRAFT ANGLE.
8. DIMENSION A6 MEASURES THE BOTTOM OF THE GLASS TO TOP OF DIE.
9. DIMENSION A7 MEASURES THE BOTTOM OF THE PACKAGE TO TOP OF DIE.

DIM	MILLIMETERS			DIM	MILLIMETERS		
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.
A	1.75	1.85	1.95	D4	7.32 REF		
A1	0.00	---	0.05	D5	6.40 REF		
A3	0.254 REF			E	5.10	5.20	5.30
A4	0.594 REF			E2	3.20	3.30	3.40
A5	0.256 REF			E3	2.67 REF		
A6	0.270 REF			E4	2.42 REF		
A7	0.971	1.014	1.052	E5	1.50 REF		
<i>b</i>	0.25	0.30	0.35	<i>e</i>	0.65 BSC		
D	9.90	10.00	10.10	K	0.45 REF		
D2	7.80	7.90	8.00	K1	0.35 REF		
D3	7.57 REF			L	0.55	0.60	0.65



**RECOMMENDED MOUNTING FOOTPRINT\***

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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